



Material Content Data Sheet



Sales Product Name		BSC052N03LS		Issued		30. July 2019		
MA#		MA005344899						
Package		PG-TDSON-8-51		Weight*		101.31 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.224	0.22	0.22	2216	2216
leadframe	inorganic material	phosphorus	7723-14-0	0.014	0.01		135	
	non noble metal	zinc	7440-66-6	0.055	0.05		538	
	non noble metal	iron	7439-89-6	1.090	1.08		10763	
wire	non noble metal	copper	7440-50-8	44.271	43.71	44.85	437009	448445
	noble metal	gold	7440-57-5	0.028	0.03	0.03	280	280
encapsulation	organic material	carbon black	1333-86-4	0.089	0.09		878	
	plastics	epoxy resin	-	4.090	4.04		40378	
	inorganic material	silicondioxide	60676-86-0	40.282	39.76	43.89	397636	438892
leadfinish	non noble metal	tin	7440-31-5	1.264	1.25	1.25	12474	12474
plating	noble metal	silver	7440-22-4	0.029	0.03	0.03	286	286
solder	noble metal	silver	7440-22-4	0.009	0.01		93	
	non noble metal	tin	7440-31-5	0.019	0.02		185	
	non noble metal	lead	7439-92-1	0.348	0.34	0.37	3431	3709
heat sink clip	inorganic material	phosphorus	7723-14-0	0.003	0.00		28	
	non noble metal	zinc	7440-66-6	0.011	0.01		112	
	non noble metal	iron	7439-89-6	0.228	0.22		2249	
	non noble metal	copper	7440-50-8	9.250	9.13	9.36	91309	93698
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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